

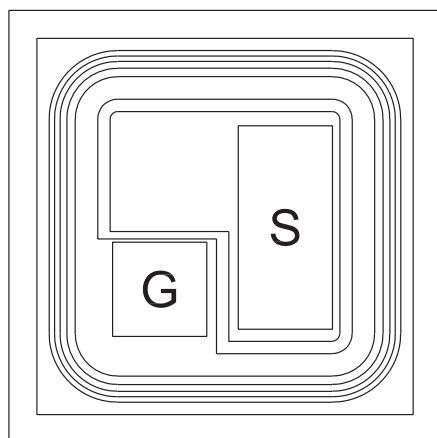
PROCESS CP354X
Small Signal MOSFET Transistor
N-Channel Enhancement-Mode Transistor Chip



PROCESS DETAILS

Process	EPITAXIAL PLANAR
Die Size	21.7 x 21.7 MILS
Die Thickness	5.5 MILS
Gate Bonding Pad Area	4.7 x 4.7 MILS
Source Bonding Pad Area	4.7 x 10.2 MILS
Top Side Metalization	Al-Si - 37,000Å
Back Side Metalization	Au - 12,000Å

GEOMETRY



BACKSIDE DRAIN

R1

GROSS DIE PER 6 INCH WAFER

51,400

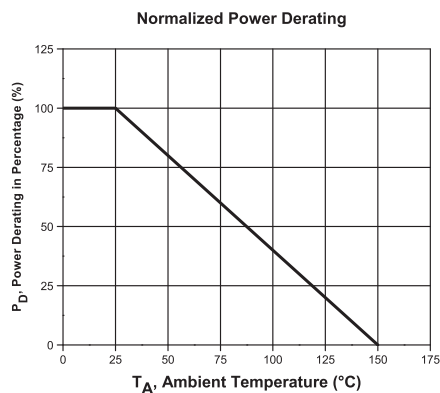
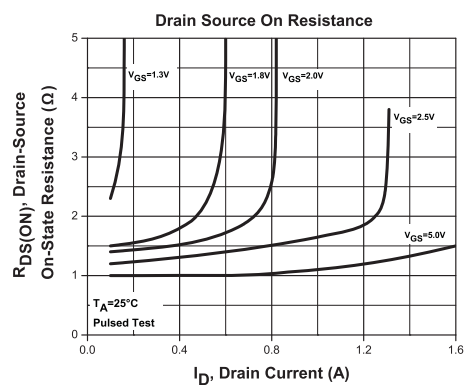
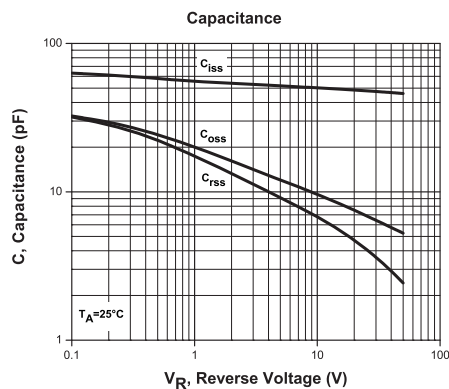
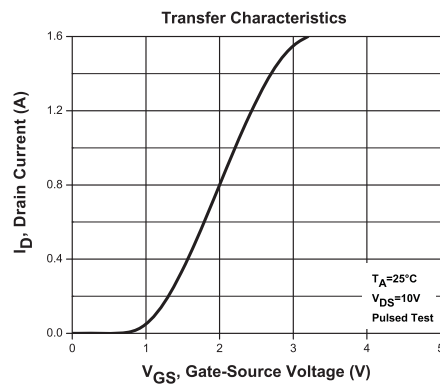
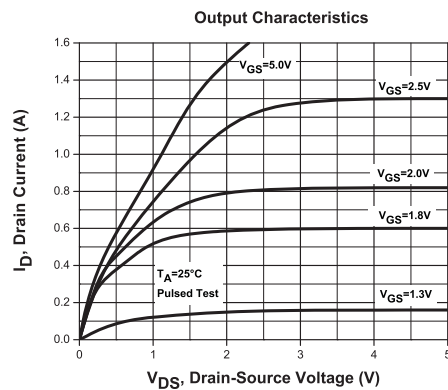
PRINCIPAL DEVICE TYPES

CMLM0305
CMLDM7003
CMPDM7003
CTLDM7003-M621

R2 (22-March 2010)

PROCESS CP354X

Typical Electrical Characteristics



R2 (22-March 2010)

BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring,
100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centrasemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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